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ttorney's Docket No.: 42P13856D

Signature

**PATENT** 

## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In Re Patent Application of:		
Rahul N. Manepalli et al.	Examiner: Dolan, Jennifer M.	
Application No.: 10/774,155	Art Unit: 2813	
Filed: February 5, 2004		
For: AN UNDERFILLING PROCESS IN A MOLDED MATRIX ARRAY PACKAGE USING FLOW FRONT MODIFYING SOLDER RESIST		
Commissioner for Patents		
P.O. Box 1450 Alexandria, VA 22313-1450		
AMENDMEN'	AND RESPONSE	
Dear Sir:		
This is in response to the Office Acti	n mailed September 2, 2005. Applicant	
respectfully requests the Examiner to enter the	e following amendments and consider the	e
following remarks.		
FIRST CLASS CER	IFICATE OF MAILING	
I hereby certify that this correspondence is being deposited postage in an envelope addressed to MAIL STOPCOMMISSIONER FOR PATENTS, P.O. Box 1450, Alexa	dria, VA 22313-1450	with sufficien
U.S. Patent and Trademark Office, Washington, D.C. 2023	on November 30, 2005  Date of Deposit	
Tanaga Massa	Date of Deposit	
Teresa Mattox Name of Person Mailing Correspond	nce	
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Serial No.: 10/774,155 Attorney Docket: 42P13856D